

Acoustical Imaging

Volume 30

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Editors

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Volume 30

 Springer

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Preface

The International Acoustical Imaging Symposium has been held continuously since 1968 as a unique forum for advanced research across the broad spectrum of topics in acoustical imaging. The interdisciplinary nature of the Symposium and the wide international participation are two of its main strengths. Scientists from around the world present papers in all fields of acoustical imaging in an informal environment conducive to lively discussion and cross-fertilization.

Acoustical Imaging remains a unique Symposium that promotes the sharing of technology, developments, methods and theory among all areas of acoustics. The fact that a loyal community of scientists has supported this Series for so many decades is evidence of its impact on the field. The Symposium series continues to thrive in a busy calendar of scientific meetings without the infrastructure of a professional society. It does so because those who attend and those who rely on the Proceedings as a well-known reference work acknowledge its value.

It is gratifying to see growth in the number of young scientists and students who attend the Symposium and who appear as authors in these Proceedings. This development is a testament to the efforts of the International Advisory Board and it bodes well for the future of the Symposium.

The 30th International Acoustical Imaging Symposium was held in Monterey, California USA during March 1–4, 2009. Volume 30 of the Proceedings marks a significant landmark in the series and accordingly contains an excellent comprehensive collection of papers presented in five major categories:

- Biomedical Imaging
- Acoustic Microscopy
- Non-Destructive Evaluation
- Systems Analysis
- Signal Analysis and Image Processing

As it has for more than 40 years, this volume of *Acoustical Imaging* offers both a broad perspective on the state of the art in the field as well as an in-depth look at its leading edge research. It is our privilege to be able to offer this collection and we express our sincere thanks to the contributing authors for making this series a continuing success.

This volume marks the passing of a colleague, friend and pioneer in the earliest days of *Acoustical Imaging*, Professor Glen Wade of the University of California, Santa Barbara. A modest biography of Dr. Wade appears in the Epilogue.

The 31st International Acoustical Imaging Symposium will be held April 10-13, 2011 in Warsaw, Poland.

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Orange, CA
Santa Barbara, CA

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Acknowledgments

It is a given that any list of acknowledgements will be incomplete and so it is with our work on *Acoustical Imaging 30*. Nonetheless, it is very important that we express our sincere gratitude to all who attend, support and contribute their work to *Acoustical Imaging*. The following wonderful people, deserving of special recognition, have offered for many years wise counsel, good friendship and selfless assistance for several Symposia; without their help *Acoustical Imaging 30* would not have been possible: Piero Tortoli, Ph.D., Iwaki Akiyama, Ph.D., Becky Jones, and Janice André.

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